



Click [here](#) for the 3D model.

| Dimensions |                  |
|------------|------------------|
| Chip Size  | 0603             |
| L          | 1.6mm +/-0.15mm  |
| W          | 0.8mm +/-0.15mm  |
| T          | 0.8mm +/-0.07mm  |
| S          | 0.7mm MIN        |
| B          | 0.35mm +/-0.15mm |

| Packaging Specifications |                        |
|--------------------------|------------------------|
| Packaging                | T&R, 330mm, Paper Tape |
| Packaging Quantity       | 15000                  |

| General Information |  |
|---------------------|--|
| Series              | SMD Comm COG                               |
| Style               | SMD Chip                                   |
| Description         | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features            | Ultra-Stable, Low Loss, Class I            |
| RoHS                | Yes  |
| Termination         | Tin  |
| Marking             | No   |
| AEC-Q200            | No   |
| Component Weight    | 3.7 mg                                     |
| Shelf Life          | 78 Weeks                                   |
| MSL                 | 1  |

| Specifications   |                        |
|--|------------------------|
| Capacitance  | 3.3 pF                 |
| Measurement Condition  | 1 MHz 1.0Vrms          |
| Capacitance Tolerance  | +/-0.25 pF             |
| Voltage DC   | 50 VDC                 |
| Dielectric Withstanding Voltage                                    | 125 VDC                |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms     |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |